

PATENTS  
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IN THE CLAIMS:

1 Claims 1-17 (canceled)

1 Claim 18 (currently amended). A substrate for receiving a die-down die and pro-  
2 viding electrical contacts re-orientated into a die-up orientation, the die-down die defin-  
3 ing electrical contacts, the substrate comprising:

4 a plurality of electrically conductive traces defining first contacts, the first con-  
5 tacts arranged in an orientation to accept connector wires for making electrical connec-  
6 tions from the electrical contacts of a single die-down die, if one was mounted,

7 the plurality of electrically conductive traces running under and from one side to  
8 the opposite side of a single die down die, if one was mounted, and

9 wherein the electrical traces define second contacts located on the opposite side  
10 relative to the first contacts, the second contacts arranged in a die up orientation, arranged  
11 to correspond to the die-up orientation of a single die-up die,

12 wherein the substrate can be placed into a package designed to accept a single die-  
13 up die, and wherein electrical connections may be made to the substrate's second contacts  
14 as if it were a single die-up die.

1 Claim 19 (previously presented). The substrate of claim 18 further comprising:

2 a single die-down die mounted to the substrate,

3 connector wires joining the electrical contacts of the die-down die to the  
4 first contacts on the conductive traces,

5 and

6 electrically conductive wires joining the second contacts on the conductive  
7 traces to contacts on a lead frame.

1 Claim 20. (canceled).

PATENTS  
112055-0040  
17732-38560.00

1 Claim 21. (previously presented). The substrate of claim 19 further comprising  
2 non-conductive means for attaching the substrate to the single die-down die.

1 Claim 22. (previously presented). The substrate of claim 18 wherein the substrate  
2 comprises a material selected from the groups consisting of ceramic and organic.

1 Claim 23. (previously presented). The substrate of claim 19 wherein the single  
2 die-down die is an integrated circuit.

1 Claim 24. (canceled).

1 Claim 25 (withdrawn). A process for re-orienting a die-down die to a die-up ori-  
2 entation, the die-down die defining electrical contacts, the process comprising the steps  
3 of:

4 forming a plurality of electrically conductive leads defining first and second con-  
5 tacts on a substrate,

6 arranging the first contacts to accept electrical connections from the electrical  
7 contacts of a die-down die, and

8 arranging the second contacts to correspond to the die-up orientation.

1 Claim 26 (withdrawn) The process of claim 25 further comprising the steps of:  
2 joining electrically conductive wires from the electrical contacts of the die-down  
3 die to the first contacts on the substrate,

4 arranging a package to receive a die-up die, the package defining third contacts  
5 arranged for receiving electrical connections to a die-up die,

6 joining electrically conductive wires from the second contacts on the substrate to  
7 the third contacts.

PATENTS  
112055-0040  
17732-38560.00

1 Claim 27 (withdrawn) The process of claim 26 further comprising the steps of:  
2 providing a lead frame within the package,  
3 forming third contacts as part of the lead frame, and  
4 forming fourth contacts as part of the lead frame, and  
5 arranging the fourth contacts to make electrical connections to a printed circuit  
6 board.

1 Claim 28 (withdrawn) The process of claim 26 further comprising the step of at-  
2 taching the substrate to the die-down die.

1 Claim 29 (withdrawn) The process of claim 26 further comprising the step of  
2 forming the substrate from a material selected from the groups consisting of ceramic and  
3 organic.

1 Claim 30 (withdrawn) The process of claim 26 wherein the die-down die is an  
2 integrated circuit.

1 Claim 31 (withdrawn) The process of claim 26 wherein the die-down die includes  
2 components attached to the die-down die.

1 Claim 32 (cancelled).

1 Claim 33. (cancelled).

1 Claim 34. (previously presented). The die attach package of claim 45 further  
2 comprising non-conductive means for attaching the substrate to the single die-down die.

1 Claim 35. (previously presented). The die attach package of claim 45 wherein the  
2 substrate comprises a material selected from the groups consisting of ceramic and or-  
3 ganic.

PATENTS  
112055-0040  
17732-38560.00

1 Claim 36. (previously presented). The die attach package of claim 45 wherein the  
2 single die-down die is an integrated circuit.

1 Claim 37. (previously presented). The die attach package of claim 45 wherein the  
2 single die-down die includes components attached to the die-down die.

1 Claim 38 (withdrawn) A process for re-orienting and connecting a die-down die  
2 in a die-up orientation and package, the die attach package defining third contact leads  
3 with a die-up orientation, the die-down die defining electrical contacts, the process com-  
4 prising the steps of:  
5 forming a plurality of electrically conductive leads defining first and second con-  
6 tacts on a substrate,  
7 arranging the first contacts to accept electrical connections from the electrical  
8 contacts of a die-down die,  
9 making electrical connections from the die-down die contact to the first contacts.  
10 arranging the second contacts to correspond to the die-up orientation,  
11 making electrical connections from the third contact to the second contacts.

1 Claim 39 (withdrawn) The process of claim 38 wherein the making of the electri-  
2 cal connections comprising the steps of:  
3 joining electrically conductive wires from the electrical contacts of the die-down  
4 die to the first contacts on the substrate,  
5 joining electrically conductive wires from the second contacts on the substrate to  
6 the third contacts.

1 Claim 40 (withdrawn) The process of claim 38 further comprising the steps of:  
2 providing a lead frame within the package,  
3 forming third contacts as part of the lead frame, and  
4 forming fourth contacts as part of the lead frame, and

PATENTS  
112055-0040  
17732-38560.00

5       arranging the fourth contacts to make electrical connections to a printed circuit  
6       board.

1       Claim 41 (withdrawn) The process of claim 38 further comprising the step of non-  
2       conductively attaching the substrate to the die-down die.

1       Claim 42 (withdrawn) The process of claim 38 further comprising the step of  
2       forming the substrate from a material selected from the groups consisting of ceramic and  
3       organic.

1       Claim 43 (withdrawn) The process of claim 38 wherein the die-down die is an  
2       integrated circuit.

1       Claim 44 (withdrawn) The process of claim 38 wherein the die-down die includes  
2       components attached to the die-down die.

1       Claim 45 (previously presented). A die attach package for receiving a single die  
2       with contacts arranged in a die-up orientation, the die attach package comprising:  
3               a substrate as defined in claim 18,  
4               a lead frame with contacts,  
5               connector wires joining the second contacts on the traces to the lead frame  
6       contacts.